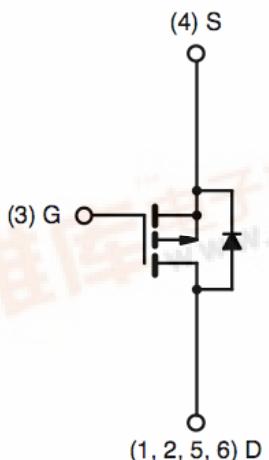


 TSM3443 -20V P-Channel Enhancement-Mode MOSFET Preliminary							
 SOT-26 Pin assignment: 1. Drain 6. Drain 2. Drain 5. Drain 3. Gate 4. Source	V_{DS} = -20V R_{Ds(on)}, V_{GS} @ -4.5V, I_{DS} @ -4.7A = 60mΩ R_{Ds(on)}, V_{GS} @ -2.5V, I_{DS} @ -3.7A = 100mΩ						
Features <ul style="list-style-type: none"> ◊ Advanced trench process technology ◊ High density cell design for ultra low on-resistance ◊ Fully Characterized Avalanche Voltage and Current ◊ Improved Shoot-Through FOM 	Block Diagram P-Channel MOSFET 						
Ordering Information <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: left;">Part No.</th> <th style="text-align: left;">Packing</th> <th style="text-align: left;">Package</th> </tr> </thead> <tbody> <tr> <td>TSM3443CX6</td> <td>Tape & Reel 3,000/per reel</td> <td>SOT-26</td> </tr> </tbody> </table>	Part No.	Packing	Package	TSM3443CX6	Tape & Reel 3,000/per reel	SOT-26	
Part No.	Packing	Package					
TSM3443CX6	Tape & Reel 3,000/per reel	SOT-26					
Absolute Maximum Rating ($T_a = 25^\circ\text{C}$ unless otherwise noted)							
Parameter	Symbol	Limit	Unit				
Drain-Source Voltage	V_{DS}	-20V	V				
Gate-Source Voltage	V_{GS}	± 12	V				
Continuous Drain Current,	I_D	-4.7	A				
Pulsed Drain Current,	I_{DM}	-20	A				
Maximum Power Dissipation	$T_a = 25^\circ\text{C}$	2	W				
	$T_a = 70^\circ\text{C}$	1.3					
Operating Junction Temperature	T_J	+150	$^\circ\text{C}$				
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$				
Thermal Performance							
Parameter	Symbol	Limit	Unit				
Junction to Foot (Drain) Thermal Resistance	$R_{\theta jf}$	30	$^\circ\text{C/W}$				
Junction to Ambient Thermal Resistance (PCB mounted)	$R_{\theta ja}$	50	$^\circ\text{C/W}$				

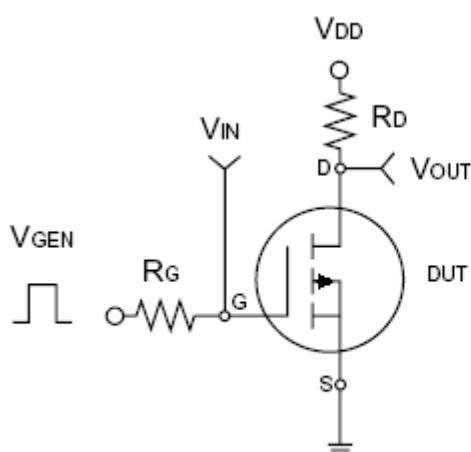
Note: Surface mounted on FR4 board t<=10sec.

Electrical Characteristics

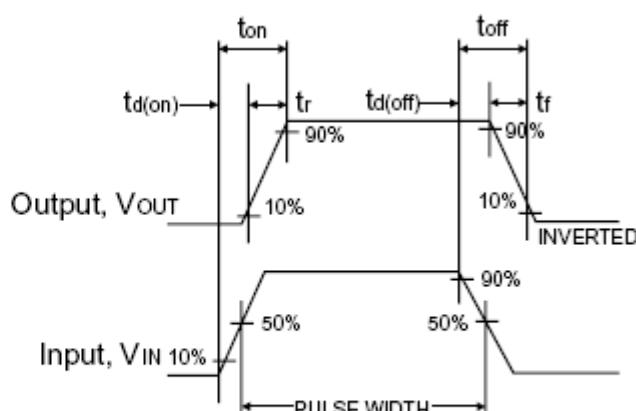
(Ta = 25 °C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = - 250uA	BV _{DSS}	-20	--	--	V
Drain-Source On-State Resistance	V _{GS} = - 4.5V, I _D = - 4.7A	R _{DS(ON)}	--	48	60	mΩ
Drain-Source On-State Resistance	V _{GS} = - 2.5V, I _D = - 1A	R _{DS(ON)}	--	80	100	
Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = - 250uA	V _{GS(TH)}	-0.6	--	-1.4	V
Zero Gate Voltage Drain Current	V _{DS} = -20V, V _{GS} = 0V	I _{DSS}	--	--	-1.0	μA
Gate Body Leakage	V _{GS} = ±12V, V _{DS} = 0V	I _{GSS}	--	--	±100	nA
On-State Drain Current	V _{DS} = -5V, V _{GS} = -4.5V	I _{D(ON)}	-15	--	--	A
Forward Transconductance	V _{DS} = -10V, I _D = - 4.7A	g _{fs}	--	11	--	S
Dynamic						
Total Gate Charge	V _{DS} = -10V, I _D = - 4.7A, V _{GS} = -4.5V	Q _g	--	6	9	nC
Gate-Source Charge		Q _{gs}	--	1.4	--	
Gate-Drain Charge		Q _{gd}	--	1.9	--	
Turn-On Delay Time	V _{DD} = -10V, R _L = 10Ω, I _D = -1A, V _{GEN} = - 4.5V, R _G = 6Ω	t _{d(on)}	--	22	35	nS
Turn-On Rise Time		t _r	--	35	55	
Turn-Off Delay Time		t _{d(off)}	--	45	70	
Turn-Off Fall Time		t _f	--	25	40	
Input Capacitance	V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz	C _{iss}	--	640	--	pF
Output Capacitance		C _{oss}	--	180	--	
Reverse Transfer Capacitance		C _{rss}	--	90	--	
Source-Drain Diode						
Max. Diode Forward Current		I _s	--	--	-1.3	A
Diode Forward Voltage	I _s = -1.3A, V _{GS} = 0V	V _{SD}	--	-0.75	-1.2	V

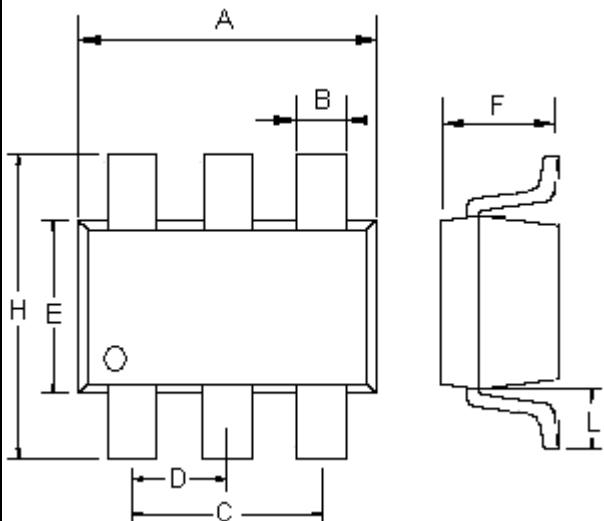
Note : pulse test: pulse width <=300uS, duty cycle <=2%



Switching Test Circuit



Switchin Waveforms

SOT-26 Mechanical Drawing

SOT-26 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.70	3.00	0.106	0.118
B	0.25	0.50	0.010	0.020
C	1.90(typ)		0.075(typ)	
D	0.95(typ)		0.037(typ)	
E	1.50	1.70	0.059	0.067
F	1.05	1.35	0.041	0.053
H	2.60	3.00	0.102	0.118
L	0.60(typ)		0.024(typ)	